

DD321606-CD

SPECIFICATION

DESCRIPTION **Chip Antenna**

PART NO. **DD321606-CD**

VERSION **V1.1**

Contents

1. Naming Rules	3
2. Antenna Specification	4
3. Antenna Dimension	5
4. Test Data	6-8
5. Layout Guide	9
6. Soldering Conditions	10
7. Packaging Information	11-12

1. Naming Rules

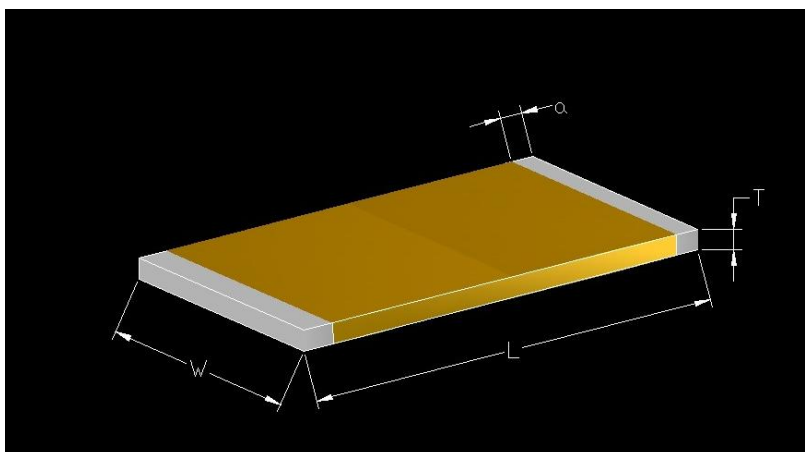
Type: DD-ABCDEF-GH

1. DD: Shortcut for DongDian Technology
2. ABCDEF: AB Length(mm) CD: Width(mm)
 EF Height(mm)
 For example: 502010 5.0mm*2.0mm
3. G: Material (C- Ceramic P-Polymer)
4. H: Feeding (S- Single D - Dual)

2. Antenna Specification

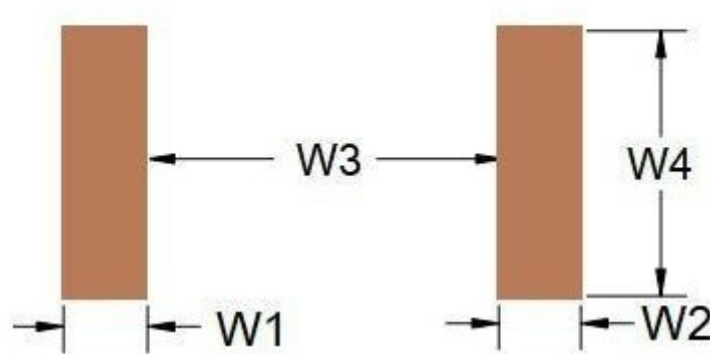
Outline Dimensions	3.2x1.6x0.6(mm)
Ground Plane	3.2x1.6(mm)
Frequency Range	2.4GHz ~ 2.5GHz
Impedance	50 Ohm Nominal
Bandwidth (under -10dB return loss)	100MHz (Typ.)
Radiation	Omni-directional
Peak Gain	1.75 dBi (Typ.)
Efficiency	60% (Typ.)
Polarization	Linear Polarization
Storage Temp	-40℃ ~ +85℃
Color	Brown

3. Antenna Dimension



Type	L	W	T	a
SKT3216	3.2 ± 0.2	1.6 ± 0.2	0.6 ± 0.2	0.4 ± 0.2

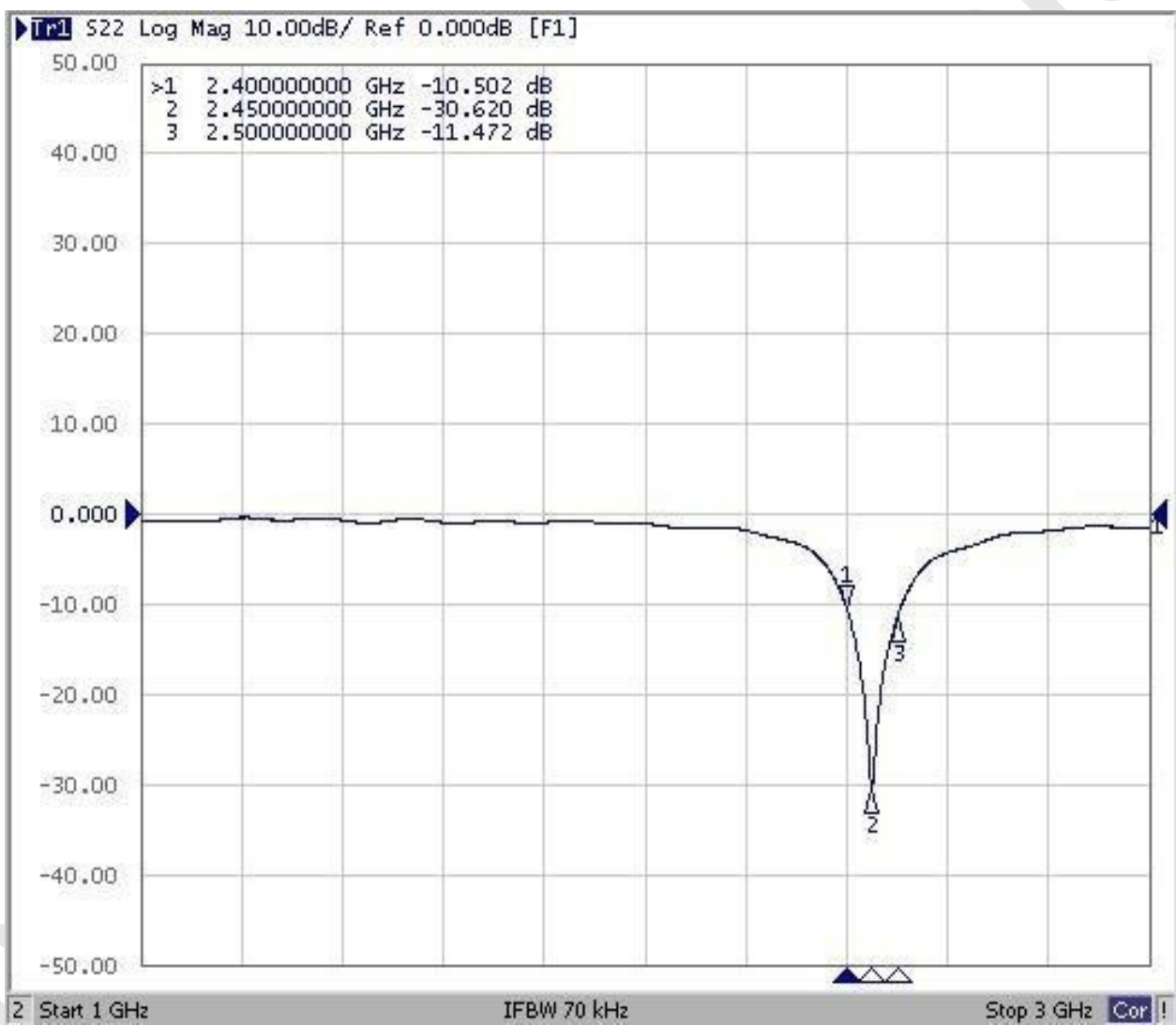
FootPrint (Unit : mm)



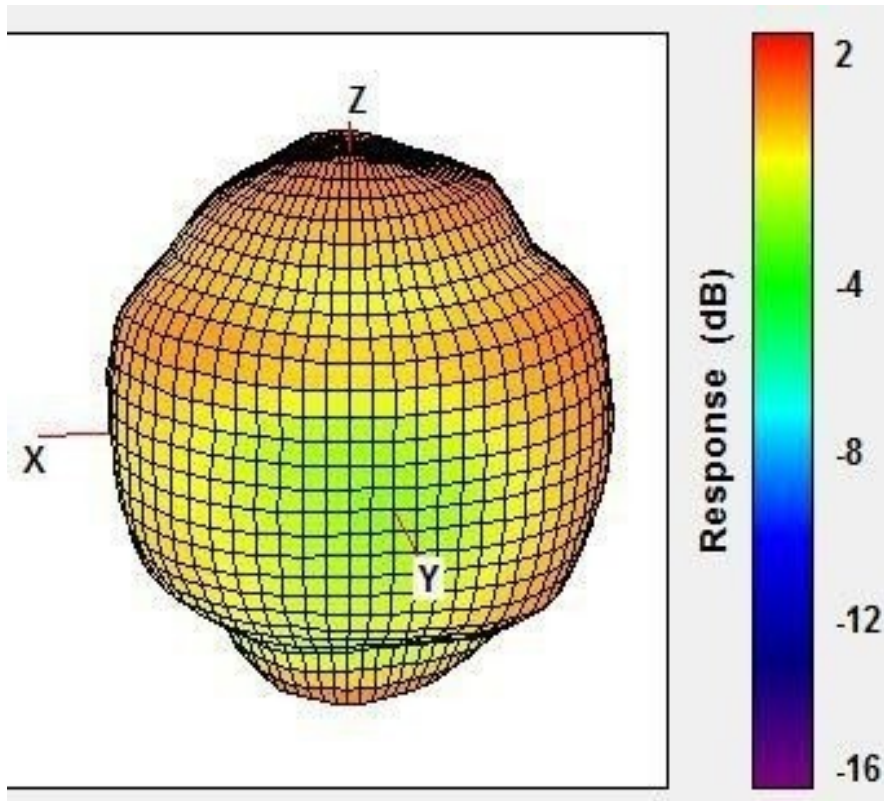
Type	W1	W2	W3	W4
SKT3216	0.4 ± 0.2	0.4 ± 0.2	2.4 ± 0.2	1.6 ± 0.2

4. Test Data:

4.1 ELECTRICAL CHARACTERISTICSS11

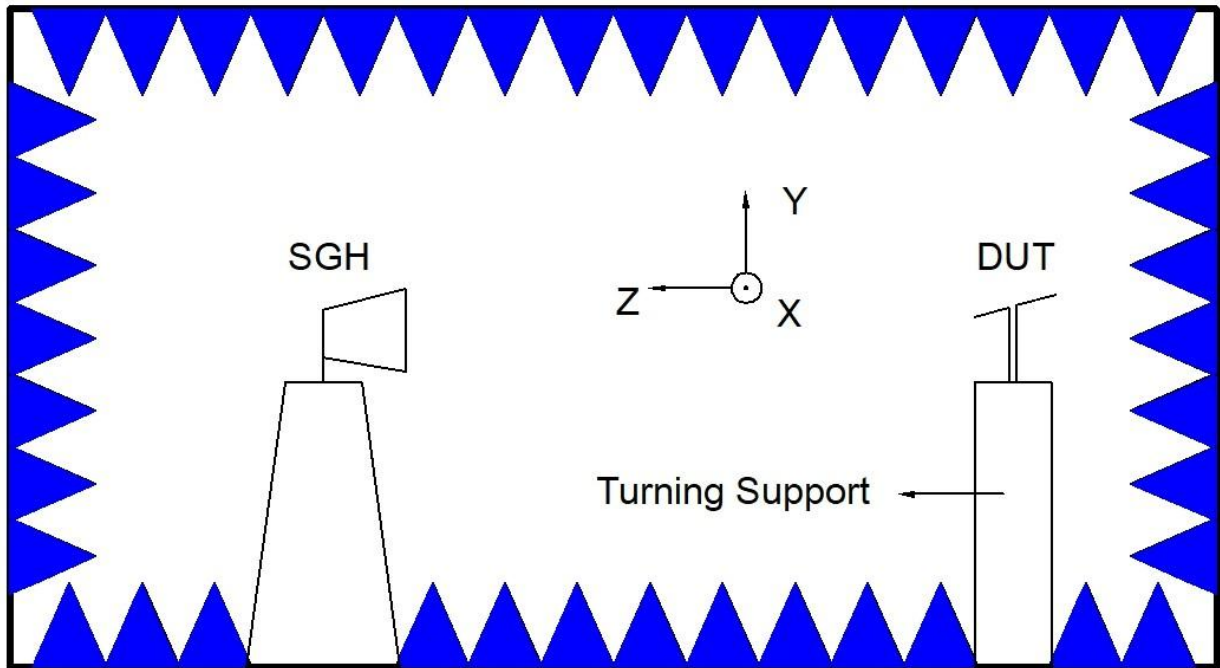


4.2 Radiation Pattern



	Efficiency	Peak Gain	Directivity
2400MHz	57.45%	1.3 dBi	2.45 dBi
2450MHz	60.65%	1.75dBi	2.89 dBi
2500MHz	56.75%	1.45dBi	2.23 dBi

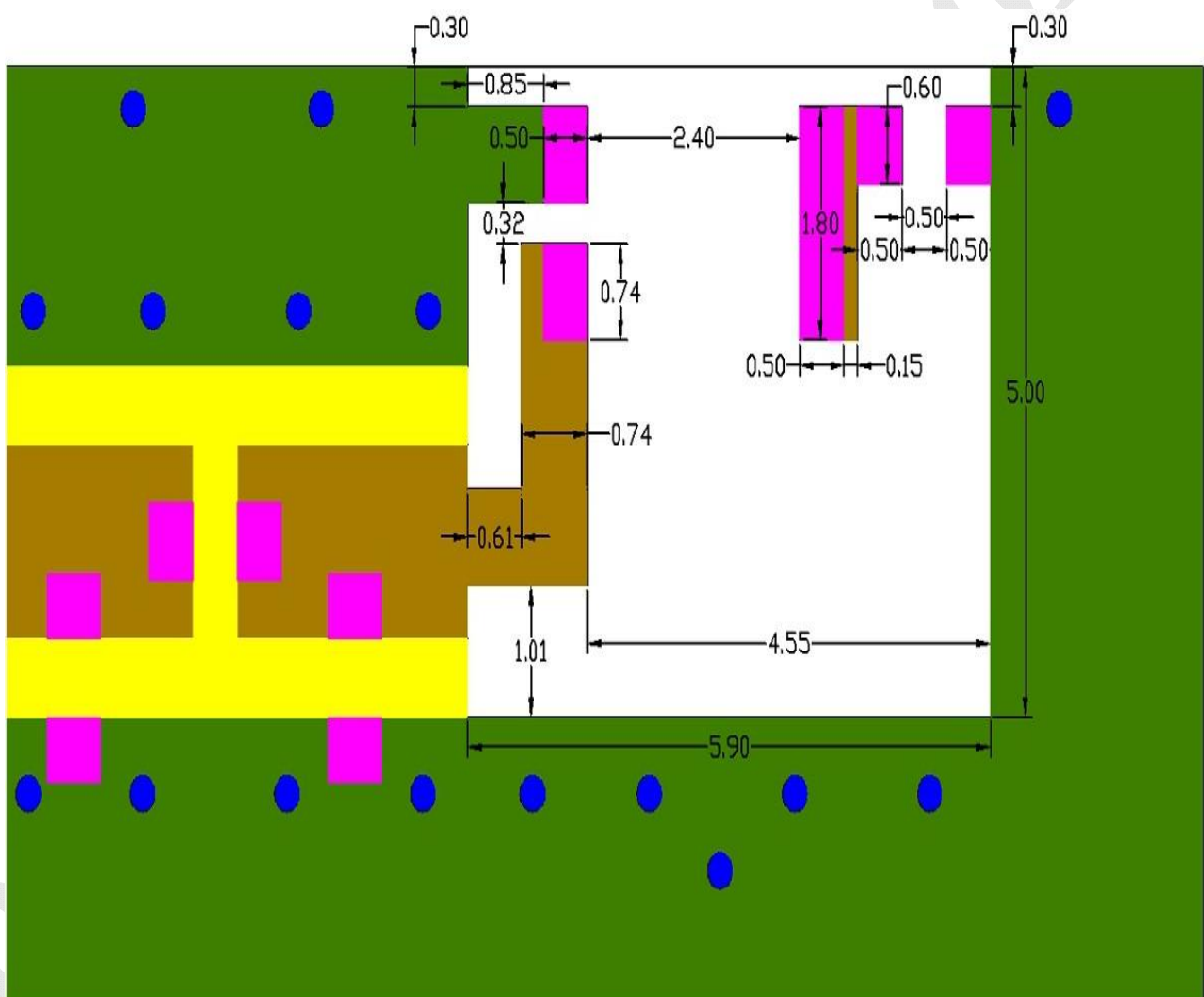
Chamber Coordinate System



5. LayoutGuide:

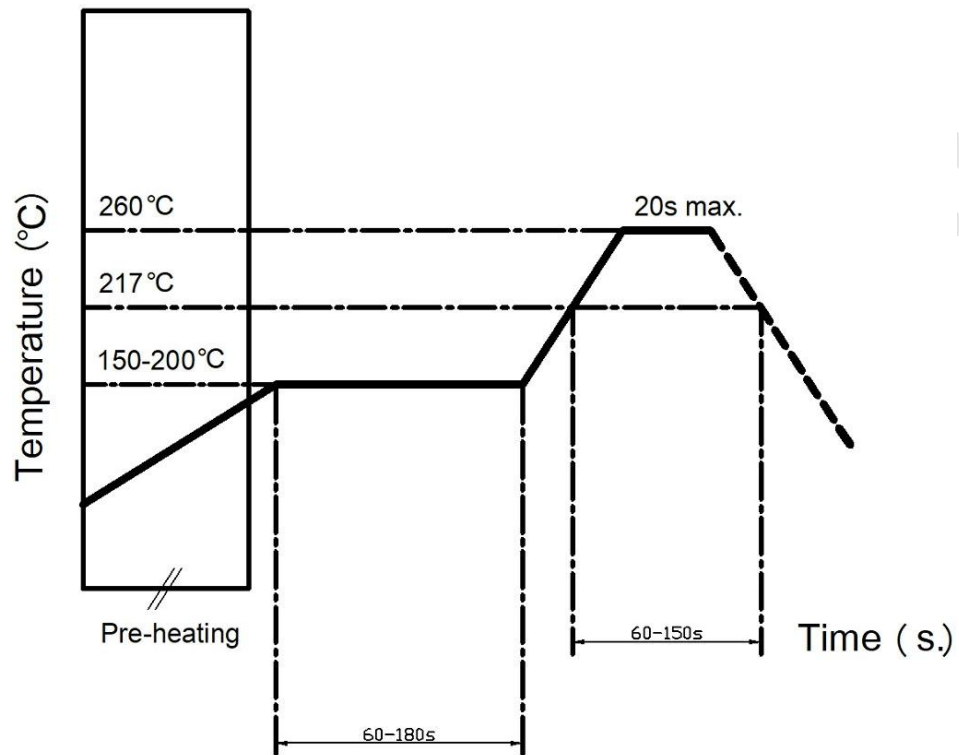
Solder Land Pattern:

Land pattern for soldering (black marking areas) is as shown below. Matching circuit is needed for good performance, when customer's device is different. ▲



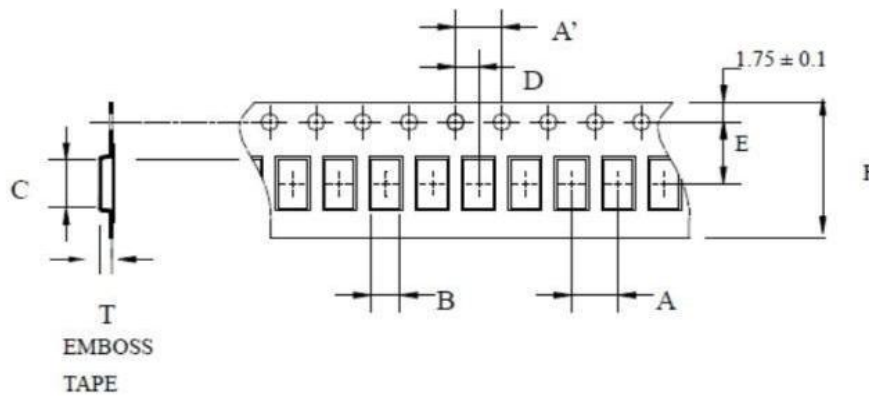
6. Soldering Conditions:

Typical Soldering Profile for Lead-free Process



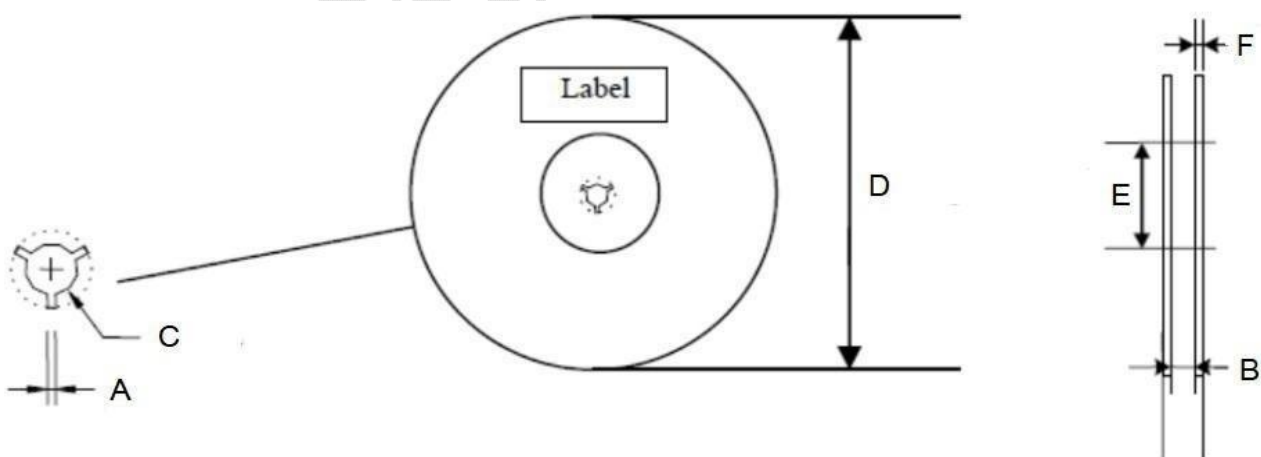
7.Taping Specifications:

Tape Dimensions (Unit: mm) & Quantity



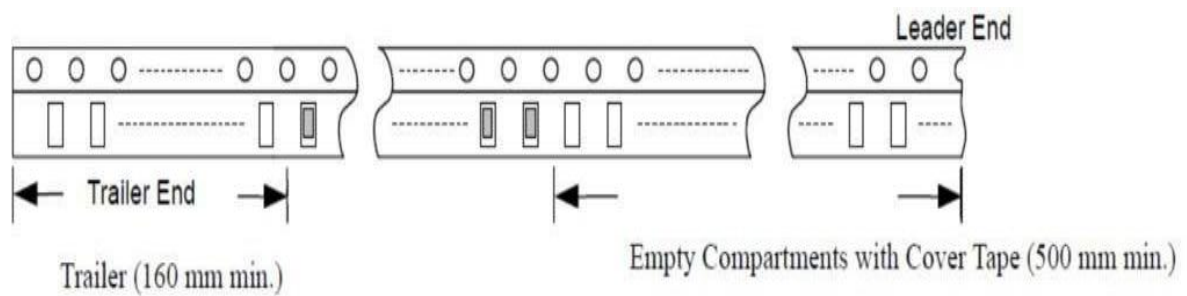
Type	A	A'	B	C	D	E	F	T	Quantity/ Reel	Type Material
SKT3216	4.0 ±0.1	4.0 ±0.1	1.95 ±0.1	3.50 ±0.1	2.0 ±0.05	3.5 ±0.1	8.0 ±0.1	0.85 ±0.1	4,000pcs	Plastic (Embossed)

Reel Dimensions (Unit: mm)



Type	A	B	C	D	E	F
SKT3216	2.3 ±0.5	17 ±0.5	13.5 ±0.5	178 ±1	75 ±3	1.4 ±0.2

Leader and Trailer Tape



Soldering Conditions:

- (1) Temperature: 5~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment